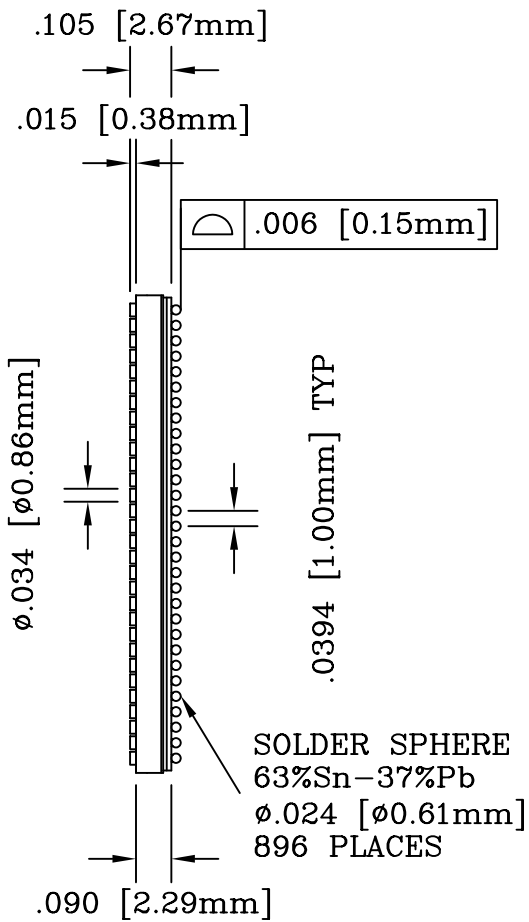
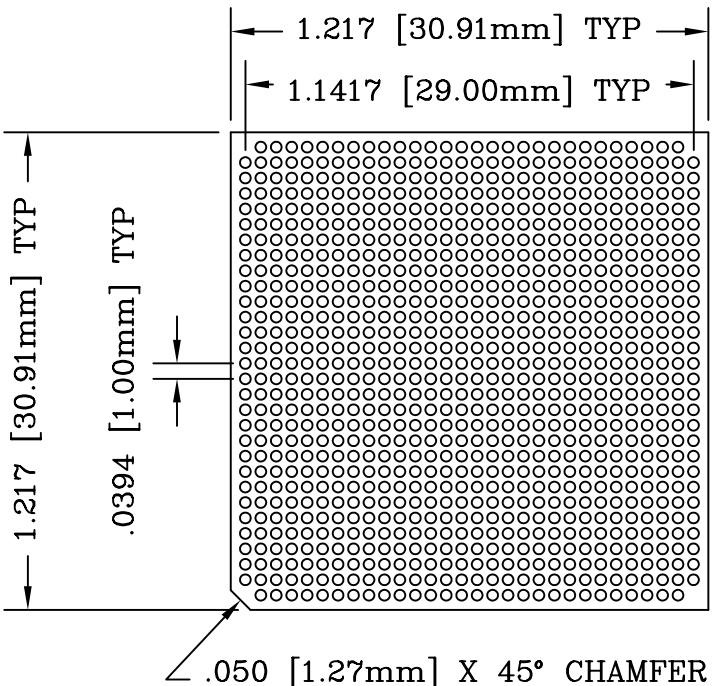


REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	04/05/04	H.N.
B	ADDED INSULATOR POLYIMIDE FILM	06/29/07	H.N.
C	UPDATED PACKAGE SIZE	02/28/08	JAG

F6884



PACKAGE SPECIFICATIONS	
PIN COUNT	= 896
LEAD PITCH	= 1.00mm
GRID SIZE	= 30X30

NOTES:

- MATERIALS:**
INSULATORS: FR-4 BLACK GLASS EPOXY, U.L. RATED 94V-0 (UNCLAD).
INSULATOR: POLYIMIDE FILM.
TERMINAL: BRASS, C36000, ASTM-B-16.
CONTACT: BeCu, C17200, ASTM-B-194.
- PLATING:**
TERMINAL: .000010 [0.000254mm] MIN. GOLD OVER .000050 [0.00127mm] MIN. NICKEL.
CONTACT: .000030 [0.000762mm] MIN. GOLD OVER .000050 [0.00127mm] MIN. NICKEL.

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED

Emulation Technology, Inc.
 — VLSI and SMT ADAPTERS and ACCESSORIES —
 759 FLYNN ROAD CAMARILLO, CA 93012 TEL:(805)383-8480 FAX:(805)383-8484

SHEET: 1 OF 1	DATE: 04/05/04	REVISION: C	ASSEMBLY DRAWING
CHECKED:	DRAWN: H.N.	ITEM: BPE-896-3-030-B	
Scale N/A	DO NOT SCALE DRAWING	DESCRIPTION: BPE-0896-3BG030-BL	